HAWAII
BUILDING INDUSTRY
Foundation

Scholarship Application

Deadline: November 15, 2025

Thank you for your interest in the Hawaii Building Industry Foundation's Scholarships. Awards will be granted to those who show promise for the future of the building & construction industry in Hawaii.

If any sections on this application do not apply to you, please write N/A in the appropriate box. Please verify that your application is complete before submitting it.

Please submit a completed application including signatures to:
scholarships@hawaiibuildingindustryfoundation.org

Any questions should be directed to - Email: scholarships@hawaiibuildingindustryfoundation.org / Phone: (808) 629-7505

Background Information

Name	
Address	
City, State, Zip	
Phone	
Personal Email (non-school or non-work)	
Year of Birth	

How did you learn about the Hawaii Building Industry Foundation scholarship?

List all high schools you have attended and dates attended.

Name of High School	Dates Attended

List all colleges/post-secondary institutions you have attended and dates attended.

Name of College/Post-Secondary Institutions	Dates Attended

What are your career goals? Why are you interested in pursuing a career and future in the building and construction industry? What college or program will you be attending?

Have you changed your career path? If so, please describe.

How will this scholarship help you achieve your goals? What does the scholarship mean to you?

Employment Information

Have you CURRENTLY or PREVIOUSLY held a job in the building or construction industry?

☐Yes

If yes, what company do you or have you work for?

☐No

If no, what company do you currently work for?

Short Essay (100 to 500 words)

Describe a challenge you have faced and how you overcame that challenge.

Acknowledgements and Signatures

- By submitting this scholarship application, I certify that I have not falsified any part of this application, nor has anyone other than myself (the applicant) completed the scholarship application and I acknowledge and understand that providing falsified information or having someone else complete and submit the application for me may result in disqualification of scholarship award.
- By submitting this scholarship application, I agree to the photo release as stated:
    - I hereby assign full copyright of any photos or video taken of me by HBIF to HBIF together with the right of reproduction either wholly or in part.
    - I grant to HBIF the permission to use photographs and/or videos separately or together, either wholly or in part, the perpetual and irrevocable and unrestricted right to use and publish video and/or photographs of me, or where I may be included for editorial trade, product advertising and such other business purpose in any manner and medium.
    - HBIF may have unrestricted use of these for whatever purpose, including advertising, with any retouching or alteration without restriction.
    - I agree that any photographs and/or videos and any reproductions shall be deemed to represent an imaginary person, and further agree that HBIF may use photographs and/or videos or any reproductions of them for any advertising purposes or for the purpose of illustrating any wording, and agree that no such wording shall be considered to be attributed to me personally unless my name is used.
    - I undertake not to prosecute or to institute proceedings, claims or demands against HBIF in respect of any usage of photographs or videos. I hereby release the HBIF from all claims and liability relating to images, video or photographs taken of me.
    - I have read this release form carefully and fully understand its meanings and implications.
- By submitting this scholarship application, I agree to the release of my contact information and any supporting documentation to the sponsors of the scholarships provided by the Foundation, if awarded; I further acknowledge that I may be contacted by donors and/or representatives of the Foundation at a later date, and I consent to my photo being used in HBIF communications.
- By submitting this scholarship application, I understand and acknowledge that all communications and notifications regarding this scholarship application will be conducted via e-mail to the e-mail address I have provided and it is my obligation to keep my contact information up to date at all times.

By submitting this scholarship application, I acknowledge all statements above.

Type or Print Full Name	***Date***

Signature of Applicant

If the applicant is under 18 years old, the application is signed by a parent or guardian who acknowledges that all statements are true and correct. If applicable, parent or guardian, type and sign. Please enter "N/A" if not applicable.

Type or Print Full Name of Parent or Guardian	***Date***

Signature of Parent or Guardian

Please submit a PDF copy of this completed application including signatures to: scholarships@hawaiibuildingindustryfoundation.org before the deadline.